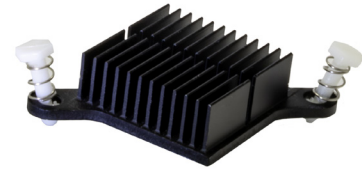


MODEL: HSB40-252510P | **DESCRIPTION:** HEAT SINK**FEATURES**

- BGA design
- push pins
- aluminum alloy
- black anodized finish

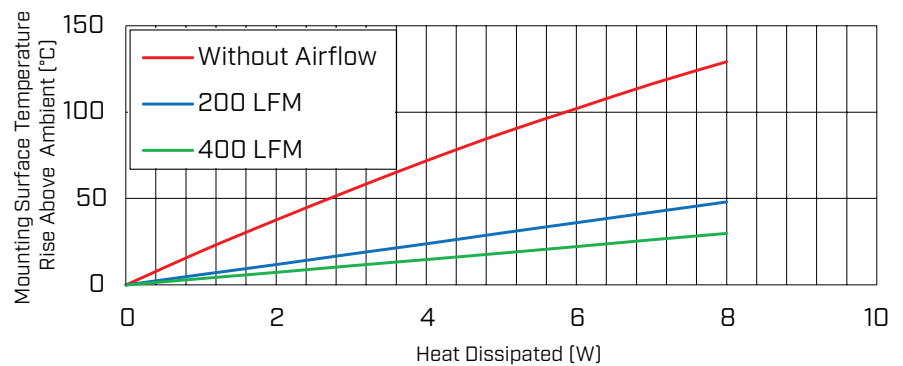
**MODEL**

	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
HSB40-252510P	17.87	19.5	6.0	3.7	4.20

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

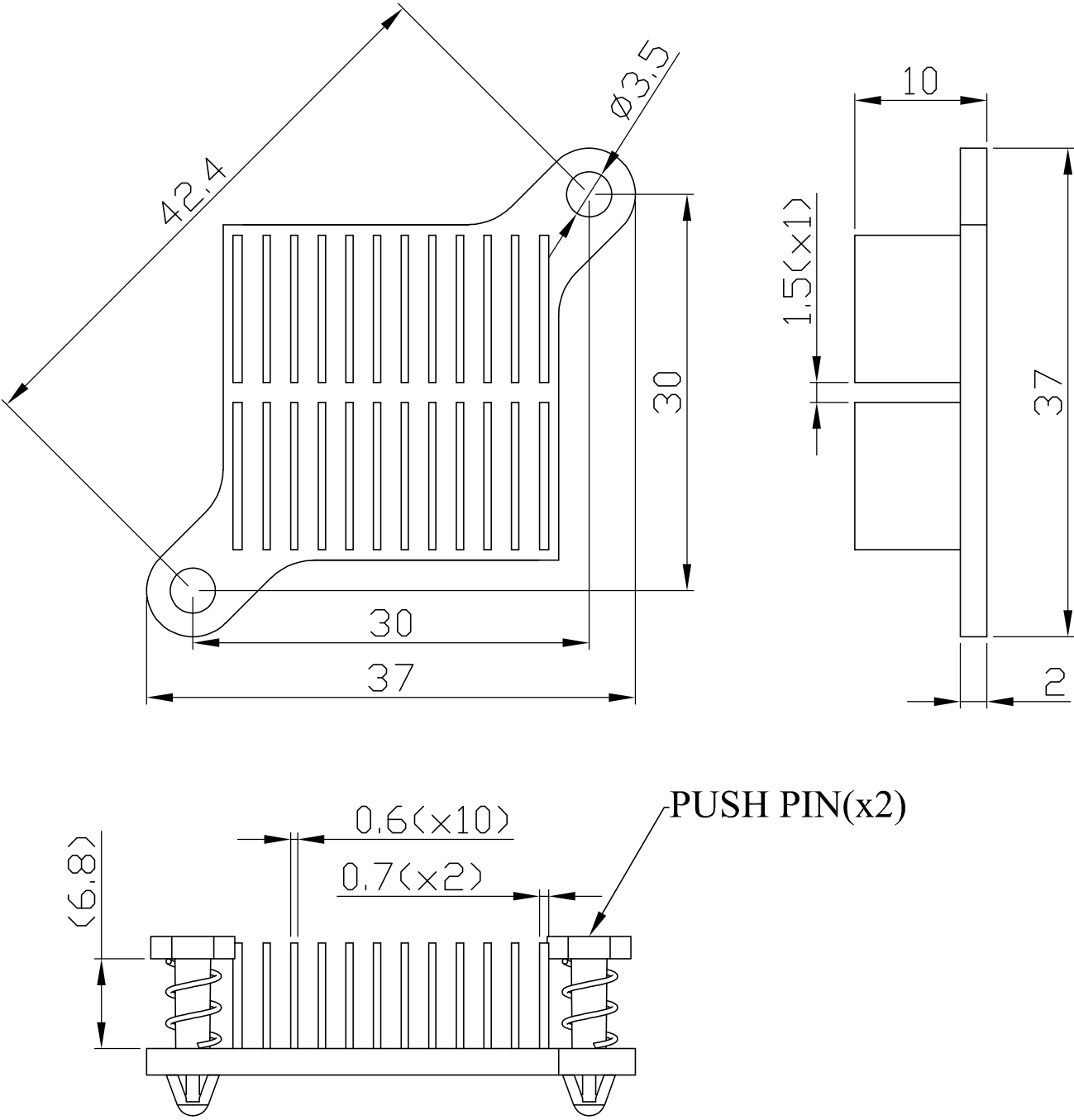
Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	19.5	6.0	3.7
2	37.6	11.8	7.3
3	55.0	17.9	11.1
4	71.8	23.8	14.7
5	87.6	30.0	18.4
6	102.0	36.0	22.2
7	116.2	42.0	26.1
8	129.1	48.0	29.8

T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	nylon 66
SPRING	spring steel, zinc plated
WEIGHT	7 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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